

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Takaaki DOMON</td><td>03/10/2005</td></tr><tr><td>Toshiyuki NAGATSUKA</td><td>03/10/2005</td></tr><tr><td>Tsutomu YASUI</td><td>03/10/2005</td></tr><tr><td>Ryoichi KONDO</td><td>03/10/2005</td></tr></tbody></table>	Name	Execution Date	Takaaki DOMON	03/10/2005	Toshiyuki NAGATSUKA	03/10/2005	Tsutomu YASUI	03/10/2005	Ryoichi KONDO	03/10/2005	
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Ryoichi KONDO	03/10/2005										
RECEIVING PARTY DATA											
Name:	TDK CORPORATION										
Street Address:	1-13-1, Nihonbashi, Chuo-ku										
City:	Tokyo										
State/Country:	JAPAN										
Postal Code:	103-8272										
PROPERTY NUMBERS Total: 1											
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>11071574</td></tr></tbody></table>	Property Type	Number	Application Number:	11071574							
Property Type	Number										
Application Number:	11071574										
CORRESPONDENCE DATA											
Fax Number:	(202)737-6776										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
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NAME OF SUBMITTER:	Jeffrey A. Wyand										
Total Attachments: 1 source=403340Murai.assn#page1.tif											

CH \$40.00 11071574

500025486

PATENT
REEL: 015844 FRAME: 0153

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned,

(1) Takaaki Domon, (2) Toshiyuki Nagatsuka,

(3) Tsutomu Yasui, (4) Ryoichi Kondo

hereby sell, assign and transfer to

TDK Corporation

(hereinafter called the Assignee), its successors and assigns, the entire right, title, and interest in and to:

the application for United States Letters Patent entitled
Circuit device and manufacturing method of the same

which was executed by the undersigned on _____
or filed on March 4, 2005 and accorded Serial No. 11/071,574
(hereinafter called the Application);

- ii) any and all inventions and improvements which are described in the Application;
- (iii) any and all United States Letters Patents which may be granted on the Application (hereinafter called the Patent);
any and all divisions, continuations, substitutes, or reissues of the Application or Patent; and
- (v) all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized that the above-mentioned assignee insert in this instrument the execution date and/or the filing date and serial number of said application.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, or reissue patent applications, execute all additional assignments and other writings and provide all reasonable assistance requested by the Assignee.

Signed at _____
this 10 day of March, 2005.

WITNESS(ES):

INVENTOR(S):

Takaaki Domon

Toshiyuki Nagatsuka

Tsutomu Yasui

Ryoichi Kondo

PATENT